

# Multilayer Ceramic Chip Capacitors

## C7563X7S1C107M280LE



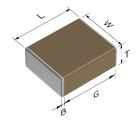






#### **TDK item description** C7563X7S1C107MT\*\*\*S

Applications	Commercial Grade
Feature	Soft Termination
Series	C7563 [EIA 3025]
Status	Production



	Size
Length(L)	7.50mm ±0.50mm
Width(W)	6.30mm ±0.50mm
Thickness(T)	3.00mm Max.
Terminal Width(B)	0.30mm Min.
Terminal Spacing(G)	
Recommended Land Pattern (PA)	5.20mm to 5.80mm
Recommended Land Pattern (PB)	1.70mm to 1.90mm
Recommended Land Pattern (PC)	6.40mm to 7.40mm

Electrical Characteristics		
Capacitance	100μF ±20%	
Rated Voltage	16VDC	
Temperature Characteristic	X7S(±22%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	1ΜΩ	

	Other	
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Blister (Plastic)Taping [330mm Reel]	
Package Quantity	1000pcs	

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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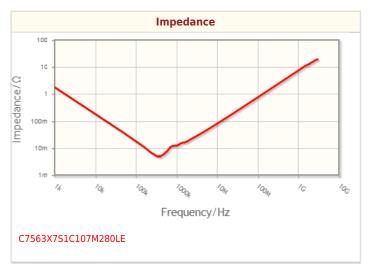


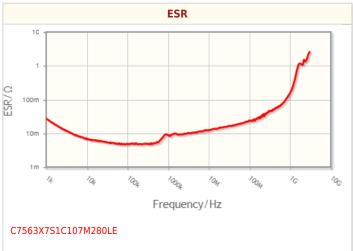


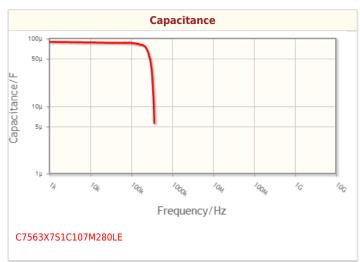


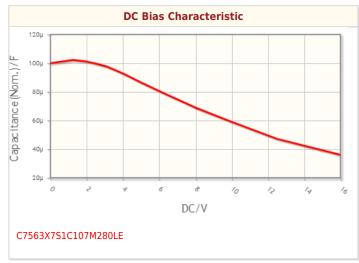


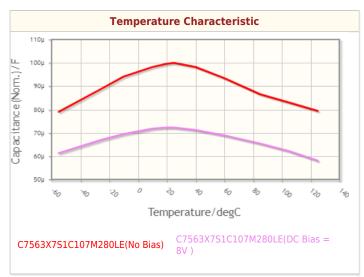
# Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

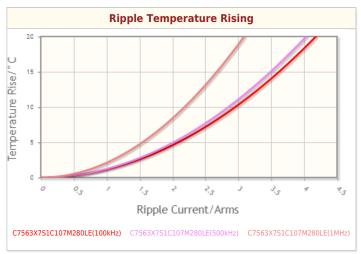












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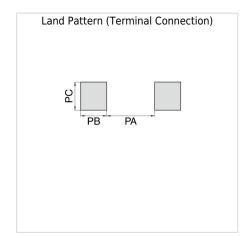








# **Associated Images**



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